

AMENDMENTS TO THE CLAIMS:

Please amend the claims as follows, substituting any amended claim(s) for the corresponding pending claim(s):

1.-8. (Canceled)

9. (Currently Amended) An integrated circuit package, comprising:

an integrated circuit die mounted on a lead frame including one or more leads or pins and at least one other portion; and

a plastic or epoxy material encapsulating at least part of the integrated circuit die and a portion of the lead frame,

wherein a portion of the at least one other portion of the lead frame remaining unencapsulated by the plastic or epoxy material is folded around sides of the encapsulated integrated circuit die and over or adjacent to a peripheral upper surface of the plastic or epoxy material.

10. (Original) The integrated circuit package of claim 9, further comprising:

a connection between a ground voltage and the portion of the lead frame folded around the sides of the encapsulated integrated circuit die and over or adjacent to the peripheral upper surface of the plastic or epoxy material.

11. (Previously Presented) The integrated circuit package of claim 9, wherein the plastic or epoxy material encapsulates exposed surfaces of the integrated circuit die, except for a sensing surface, and wire bonds connecting the integrated circuit die to portions of the lead frame.

12. (Original) The integrated circuit package of claim 9, wherein portions of the lead frame are folded around each side of the encapsulated integrated circuit die.

13. (Currently Amended) ~~The~~ An integrated circuit package ~~of claim 9, comprising:~~
an integrated circuit die mounted on a lead frame including one or more leads or pins; and
a plastic or epoxy material encapsulating at least part of the integrated circuit die and a
portion of the lead frame,
wherein a portion of the lead frame remaining unencapsulated by the plastic or epoxy
material is folded around sides of the encapsulated integrated circuit die and over or adjacent to a
peripheral upper surface of the plastic or epoxy material, and
wherein a ~~a~~ first portion of the lead frame folded around a first side of the encapsulated
integrated circuit die includes an opening therethrough providing access for a connector to leads or
pins electrically connected to the integrated circuit die.

14. (Currently Amended) ~~The~~ An integrated circuit package ~~of claim 9, comprising:~~
an integrated circuit die mounted on a lead frame including one or more leads or pins; and
a plastic or epoxy material encapsulating at least part of the integrated circuit die and a
portion of the lead frame,

wherein a portion of the lead frame remaining unencapsulated by the plastic or epoxy
material is folded around sides of the encapsulated integrated circuit die and over or adjacent to a
peripheral upper surface of the plastic or epoxy material, and

wherein portions of the lead frame are folded only around edges of the encapsulated
integrated circuit die not including leads or pins electrically connected to the integrated circuit die.

15. (Original) The integrated circuit package of claim 9, wherein:

a first portion of the lead frame is folded around a side of the encapsulated integrated circuit
die; and

a second portion of the lead frame extending from the first portion is folded over a peripheral
upper surface of the encapsulated integrated circuit die.

16. (Original) The integrated circuit package of claim 9, wherein:

a first portion of the lead frame is folded around a side of the encapsulated integrated circuit die; and

a second portion of the lead frame extending from the first portion is folded adjacent to and level with a peripheral upper surface of the encapsulated integrated circuit die.

17. (Previously Presented) An integrated circuit package, comprising:

a lead frame including a die paddle, one or more leads or pins, and portions extending from the die paddle;

an integrated circuit die mounted on the die paddle;

a plastic or epoxy material encapsulating exposed surfaces of the integrated circuit die except for a sensing surface,

wherein the portions of the lead frame extending from the die paddle are folded around sides of the encapsulated integrated circuit die and over or adjacent to peripheral upper surfaces of the encapsulated integrated circuit die.

18. (Previously Presented) The integrated circuit package of claim 17, wherein the portions extending from the die paddle include openings around the pins or leads.

19. (Previously Presented) The integrated circuit package of claim 17, wherein the portions extending from the die paddle project from peripheral edges of the die paddle not adjacent to the pins or leads.

20. (Original) A lead frame strip for an integrated circuit package, comprising:

at least one lead frame, the lead frame including:

a die paddle on which an integrated circuit will be mounted;

a plurality of structures which will be formed into pins or leads for the integrated circuit package; and

portions extending from the die paddle which will be folded around sides of the integrated circuit package and over or adjacent to a peripheral upper surface of the integrated circuit package to form an electrostatic discharge ring.